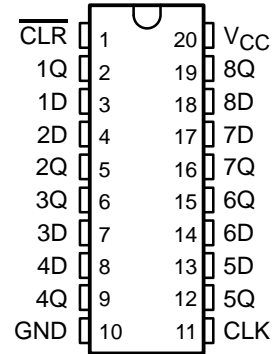


# SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

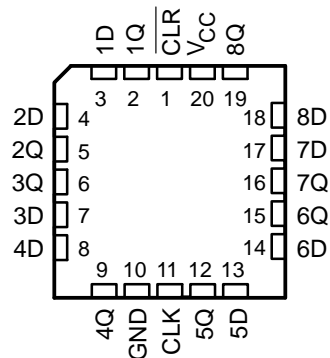
SCLS375E – JUNE 1997 – REVISED APRIL 2002

- Inputs Are TTL-Voltage Compatible
- Contain Eight Flip-Flops With Single-Rail Outputs
- Direct Clear Input
- Individual Data Input to Each Flip-Flop
- Applications Include:
  - Buffer/Storage Registers
  - Shift Registers
  - Pattern Generators
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

SN54AHCT273 . . . J OR W PACKAGE  
SN74AHCT273 . . . DB, DGV, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54AHCT273 . . . FK PACKAGE  
(TOP VIEW)



## description

These devices are positive-edge-triggered D-type flip-flops with a direct clear (CLR) input.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D input has no effect at the output.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHCT273N	SN74AHCT273N
	SOIC – DW	Tube	SN74AHCT273DW	AHCT273
		Tape and reel	SN74AHCT273DWR	
	SOP – NS	Tape and reel	SN74AHCT273NSR	AHCT273
	SSOP – DB	Tape and reel	SN74AHCT273DBR	HB273
	TSSOP – PW	Tape and reel	SN74AHCT273PWR	HB273
TVSOP – DGV	Tape and reel	SN74AHCT273DGVR	HB273	
–55°C to 125°C	CDIP – J	Tube	SNJ54AHCT273J	SNJ54AHCT273J
	CFP – W	Tube	SNJ54AHCT273W	SNJ54AHCT273W
	LCCC – FK	Tube	SNJ54AHCT273FK	SNJ54AHCT273FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2002, Texas Instruments Incorporated

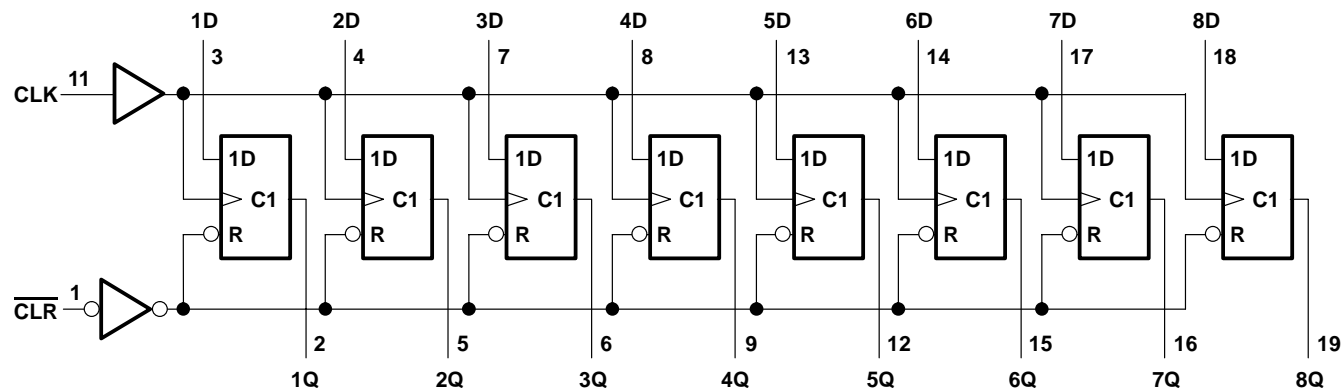
# SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

SCLS375E – JUNE 1997 – REVISED APRIL 2002

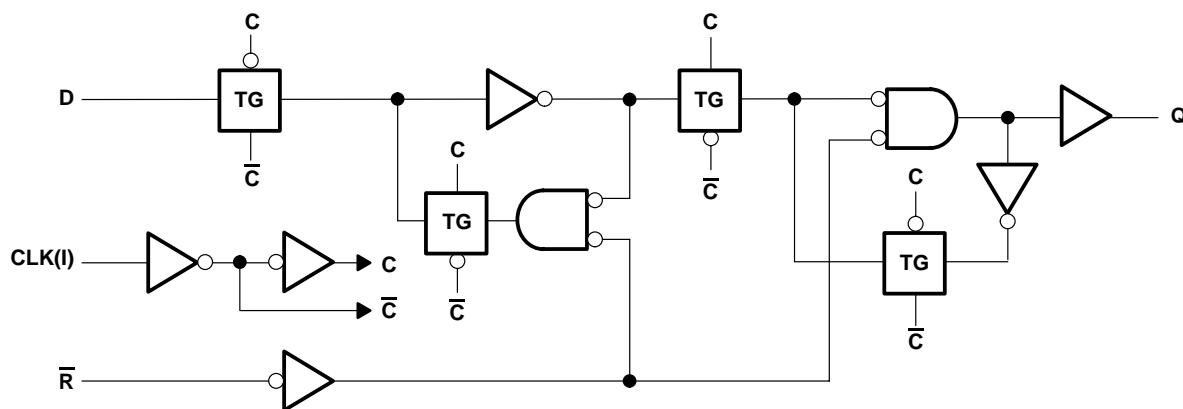
FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT
$\overline{\text{CLR}}$	CLK	D	Q
L	X	X	L
H	$\uparrow$	H	H
H	$\uparrow$	L	L
H	L	X	$Q_0$

## logic diagram (positive logic)



## logic diagram, each flip-flop (positive logic)



# SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

SCLS375E – JUNE 1997 – REVISED APRIL 2002

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Output voltage range, $V_O$ (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through $V_{CC}$ or GND	±75 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package	70°C/W
DGV package	92°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

	SN54AHCT273		SN74AHCT273		UNIT
	MIN	MAX	MIN	MAX	
$V_{CC}$ Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$ High-level input voltage	2		2		V
$V_{IL}$ Low-level input voltage		0.8		0.8	V
$V_I$ Input voltage	0	5.5	0	5.5	V
$V_O$ Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$ High-level output current		–8		–8	mA
$I_{OL}$ Low-level output current		8		8	mA
$\Delta t/\Delta v$ Input transition rise or fall time		20		20	ns/V
$T_A$ Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

SCLS375E – JUNE 1997 – REVISED APRIL 2002

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AHCT273		SN74AHCT273		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I <sub>OH</sub> = -8 mA		3.94			3.8		3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	4.5 V			0.1			0.1	V	
	I <sub>OL</sub> = 8 mA				0.36		0.44	0.44		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*	±1	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			4		40	40	μA	
ΔI <sub>CC</sub> †	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	1.5	mA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		2.5	10			10	pF	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

## timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 25°C		SN54AHCT273		SN74AHCT273		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>w</sub>	Pulse duration	CLR low	5		6		6	ns
		CLK high or low	5		6.5		6.5	
t <sub>su</sub>	Setup time	Data before CLK↑	5		5		5	ns
		CLR before CLK↑	2.5		2.5		2.5	
t <sub>h</sub>	Hold time, data after CLK↑		0		0		0	ns

## switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN54AHCT273		SN74AHCT273		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			C <sub>L</sub> = 15 pF	75**	120**		65**		65	MHz	
			C <sub>L</sub> = 50 pF	50	75		45		45		
t <sub>PHL</sub>	CLR	Q	C <sub>L</sub> = 15 pF		7.5**	10**	1**	11.6**	1	11.6	ns
t <sub>PLH</sub>	CLK	Q	C <sub>L</sub> = 15 pF		5.5**	7.5**	1**	8.8**	1	8.8	ns
t <sub>PHL</sub>					5.8**	8.2**	1**	10**	1	10	
t <sub>PHL</sub>	CLR	Q	C <sub>L</sub> = 50 pF		8.5	11	1	12.6	1	12.6	ns
t <sub>PLH</sub>	CLK	Q	C <sub>L</sub> = 50 pF		6.5	8.5	1	9.8	1	9.8	ns
t <sub>PHL</sub>					6.8	9.2	1	11	1	11	
t <sub>sk(o)</sub>			C <sub>L</sub> = 50 pF			1***			1	ns	

\*\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



**SN54AHCT273, SN74AHCT273**  
**OCTAL D-TYPE FLIP-FLOPS**  
**WITH CLEAR**

SCLS375E – JUNE 1997 – REVISED APRIL 2002

**noise characteristics,  $V_{CC} = 5\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 4)**

PARAMETER	SN74AHCT273			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic $V_{OL}$		0.76		V
$V_{OL(V)}$ Quiet output, minimum dynamic $V_{OL}$		-0.48		V
$V_{OH(V)}$ Quiet output, minimum dynamic $V_{OH}$		4.4		V
$V_{IH(D)}$ High-level dynamic input voltage		2		V
$V_{IL(D)}$ Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

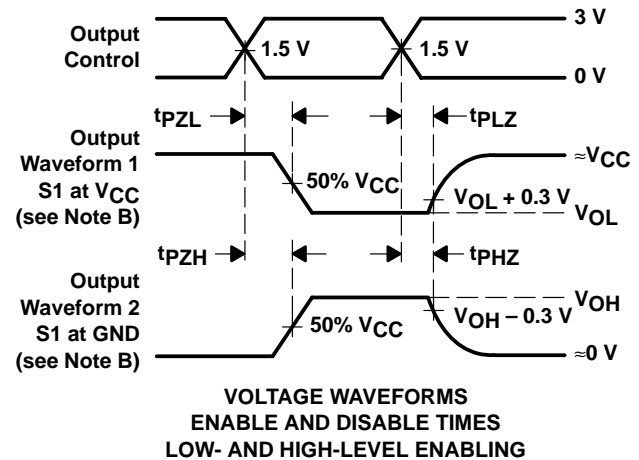
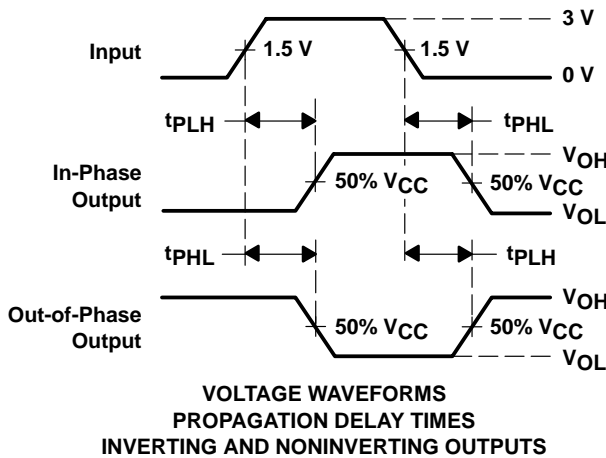
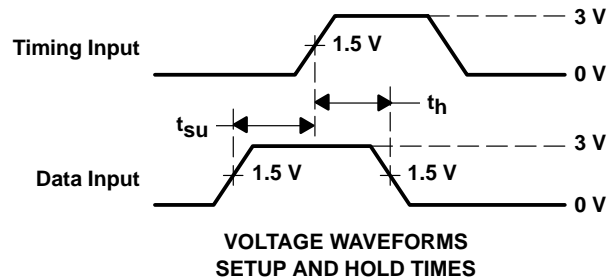
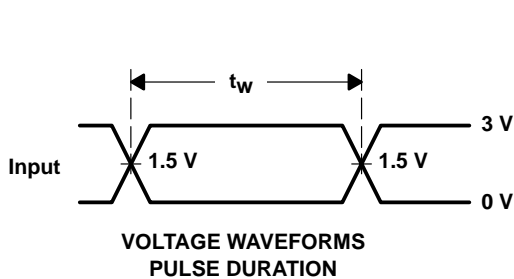
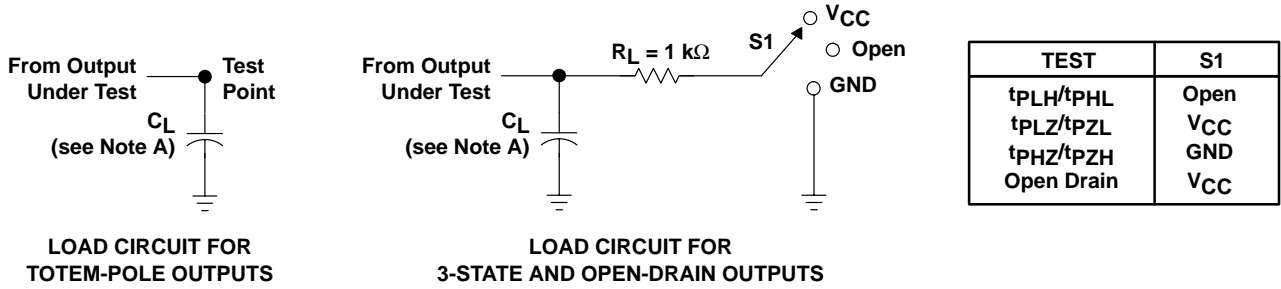
**operating characteristics,  $T_A = 25^\circ\text{C}$**

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load, $f = 1\text{ MHz}$	27	pF

# SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

SCLS375E – JUNE 1997 – REVISED APRIL 2002

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .  
 D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74AHCT273DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273DGV	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273DGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273DVG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHCT273N	<a href="#">Samples</a>
SN74AHCT273NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHCT273N	<a href="#">Samples</a>
SN74AHCT273NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>
SN74AHCT273NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT273	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74AHCT273PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>
SN74AHCT273PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB273	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT273DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHCT273DGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT273DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AHCT273NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AHCT273PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT273DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74AHCT273DGVR	TVSOP	DGV	20	2000	367.0	367.0	35.0
SN74AHCT273DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AHCT273NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AHCT273PWR	TSSOP	PW	20	2000	367.0	367.0	38.0

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)



## Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

### Наши контакты:

**Телефон:** +7 812 627 14 35

**Электронная почта:** [sales@st-electron.ru](mailto:sales@st-electron.ru)

**Адрес:** 198099, Санкт-Петербург,  
Промышленная ул, дом № 19, литера Н,  
помещение 100-Н Офис 331